Embedding of printed electronic interconnections in additively manufactured metal components

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Ultrasonic Additive Manufacturing (UAM) is an advanced hybrid manufacturing technology, which enables the embedding of electronic components and interconnections within solid metal structures, due to the low temperature/high plastic flow encountered during ultrasonic bonding. The UAM process is based on the ultrasonic metal welding of thin metal foils in a layer-by-layer fashion.

This work summarises the recent advances towards integration of UAM with printed electronics and other advanced manufacturing technologies for the encapsulation of conductive tracks and pre-packaged electronic components between the interfaces of the welded foils.

1st approach:
Screen printing was used to dispense a layer of isotropic conductive adhesive, between two layers of screen printed insulating polymer material, on a UAM fabricated substrate. Then the structure was encapsulated by resuming the welding process.

Advantages:
- No need for extra machining step - flexibility.
- The printing process can be controlled accurately.

Disadvantages:
- Short circuits may occur due to roughness of the substrate.
- There is a maximum limit in the thickness of the dielectric.
- Manufacturing in 3D is challenging.

2nd approach:
The aluminium foils were selectively anodised prior to welding. Holes were drilled in the desired locations to work as through-hole vias. A direct write system was used for depositing the conductive tracks and filling of the vias. Electrical components can be placed in cavities.

Advantages:
- The process is unaffected by substrate’s roughness.
- Good electrical insulation and thermal management can be achieved.
- Through-hole vias can be manufactured.

Disadvantages:
- An extra chemical treatment and machining pre-processing step is added.
- Intense process parameters can cause cracks in the alumina.

Alkaios Bournias-Varotsis1), Ji Li1), Ross J. Friel1), Russell A. Harris1)
1) Wolfson School of Mechanical and Manufacturing Engineering, Loughborough University, Loughborough, UK, a.bournias-varotsis@lboro.ac.uk